

Apparel

Product Data Sheet



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Adhesives, Coatings, Specialty Films & Seam Tape

Submitted by: E Toner

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Version: 3

PRODUCT DESCRIPTION:

3415

This product is a soft elastomeric adhesive. It is designed to be used in Sewfree® applications on heat sensitive fabrics where low temperature activation and high elasticity is required. Fabrics that are bonded using this adhesive exhibit excellent wash resistance and retain most of their elasticity.

SUGGESTED APPLICATIONS:

Intimates: V-fold and lay-down edge treatment; gasket cut wing; fully bonded wing; embellishment

Outerwear/ Performance: Overlap seams; pocket attachment; zipper attachment; die cut openings; hems

PRODUCT BENEFITS:

The product offers activation temperatures lower than or equal to Bemis 3206D, higher elasticity (lower modulus and higher recovery) than Bemis 3206D and has excellent bond strength to various fabrics.

COMPOSITION:

Ester Polyurethane

THERMAL & PHYSICAL PROPERTIES

- Color: Clear
- Weight: 31 gm/m² (per 25 µm)
- Release Liner: Silicone coated paper
- Gauge: 25 µm (.001"), 50 µm (.002"), 75 µm (.003")
- Width: 1524 mm (60 "); Product can be slit to requested widths, no less than 4mm (.16 ")
- Hand: Soft
- Wash: Excellent up to 50 °C
- Modulus and Recovery:

Gauge	Modulus of 25.4mm (1") wide sample		Recovery after 100% elongation at a rate of 304mm (12") per minute
	@ 40% of original length	@ 100% of original length	
25 µm (.001")	1.8 N (0.4 lbs)	4.2 N (0.93 lbs)	97%
50 µm (.002")	3.6 N (0.8 lbs)	6.2 N (1.4 lbs)	96%
75 µm (.003")	5.7N (1.28 lbs)	6.7N (1.5 lbs)	97%

- Softening Point: 83 °C
- Melt Flow Index: 45 dg/min Condition: 175 °C / 2.16 Kg Load
- Glue Line Temperature¹: 120 °C to 130 °C
- Recommended Bonding Conditions²:
 - Flat Press:
 - Machine Setting: 120 °C to 130 °C
 - Dwell Time: 20 to 30 seconds
 - Pressure: 2.8 to 4.2 Bar (40 to 60 psi)
 - Continuous Bonding Machine:
 - Machine Setting: 200 °C to 250 °C
 - Speed: 1.5 to 2.0 m/min
 - Pressure: 1.0 Bar (14.3 psi)

¹ Glue Line Temperature (GLT) refers to the temperature of the adhesive in the bonding process. Glue line temperature must be measured to receive accurate machine settings.² Recommended bonding conditions will vary between different machinery and fabrics. The recommended conditions stated are a starting point only. Optimal bonding conditions should be established by the factory for the specific application.

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